

<b>Subject:</b>	Pertanika Rewiew: Paper O11
<b>From:</b>	INTROP Colloquium 2015 (kolokium2015.introp@gmail.com)
<b>To:</b>	;
<b>Bcc:</b>	absuriani@yahoo.com;
<b>Date:</b>	Wednesday, February 10, 2016 4:26 PM

Assalamualaikum,

As been promised, attached is the paper need to be reviewed entitled

***Intermetallic Growth of SAC237 Solder Paste Reinforced with 0.01wt.% MWCNT***

Please return to the secretariat the reviewing form before Friday (19 February 2016).

Thanks for your time and cooperation.

**Best regards,**

**Nazlia Girun**

**03-89467009**

Secretariat

**INTROP Colloquium 2015**

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## **Attachments**

- O11V1.docx (673.12KB)
- Manuscript REVIEWING GUIDE rev.7-2015.doc (444.50KB)
- Manuscript REVIEWING KIT [SPECIAL ISSUE] rev.9-2015.doc (523.50KB)